

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1738eg#pbf

(Engineering Calculation)

SSOP

(printed on: 2020-07-11 20:15:16)

TOTAL MASS (g) : 0.149443

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003584 | 1000000 | 23982.4492188 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.058880 | 975000 | 393997.375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001449 | 24000 | 9696.02832031 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000018 | 300 | 120.447563171 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000042 | 700 | 281.044311523 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.060389 | 1000000 | 404094.875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002831 | 1000000 | 18941.2675781 | | |
| | | External Plating Total: | | | | 0.002831 | 1000000 | 18941.2675781 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000483 | 1000000 | 3232.00976562 | | |
| Internal Plating Total: | | | | 0.000483 | 1000000 | 3232.00976562 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001041 | 750000 | 6965.88378906 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000347 | 250000 | 2321.96142578 | | |
| Die Attach Total: | | | | 0.001388 | 1000000 | 9287.84570312 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.008259 | 103000 | 55265.3554688 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.071761 | 895000 | 480190.96875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000160 | 2000 | 1070.64489746 | | |
| | | Encapsulation Total: | | | | 0.080180 | 1000000 | 536526.9375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000588 | 1000000 | 3934.62036133 | | |
| | | | | | TOTAL MASS (g) : | 0.149443 | | |